# LN69

### GaAs Infrared Light Emitting Diode

#### For optical control systems

#### Features

- High-power output, high-efficiency:  $I_e = 3.5 \text{ mW/sr} \text{ (min.)}$
- Emitted light spectrum suited for silicon photodetectors
- Good radiant power output linearity with respect to input current
- Long lifetime, high reliability
- $\phi$ 3 plastic package

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	75	mW	
Forward current	I <sub>F</sub>	50	mA	
Pulse forward current *	I <sub>FP</sub>	1	Α	
Reverse voltage	V <sub>R</sub>	3	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: f = 100 Hz, Duty cycle = 0.1%

#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I <sub>R</sub>	$V_R = 3 V$		5.0	10	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 50 \text{ mA}$	N.	1.3	1.5	V
Center radiant intensity	Ie	$I_{\rm F} = 20 \mathrm{mA}$	3.5	2.		mW/sr
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$	OSIT	35		pF
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 50 \mathrm{mA}$		940		nm
Spectral half band width	Δλ	$I_{\rm F} = 50 \mathrm{mA}$		50		nm
Half-power angle	θ	The angle when the radiant power is halved.		15		0

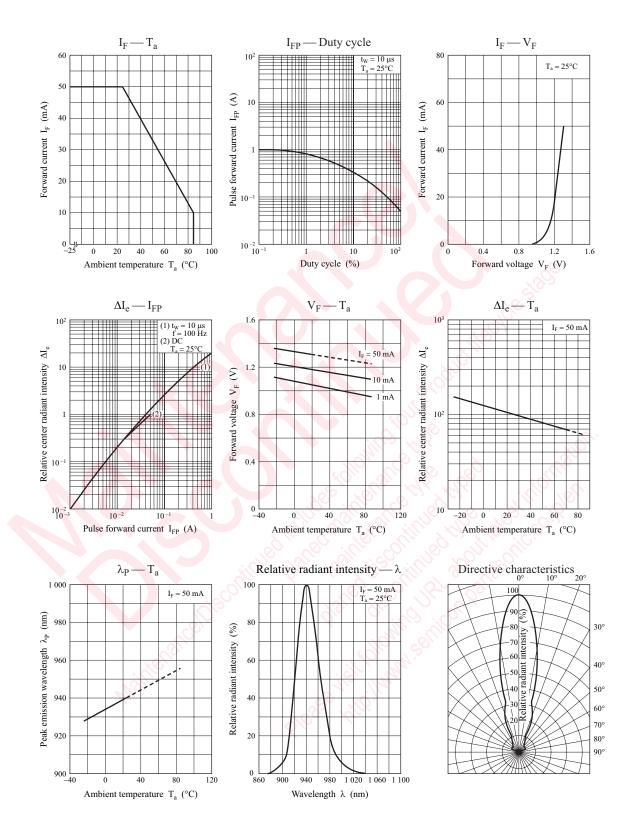
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Cutoff frequency: 1 MHz

$$f_C: 10 \times \log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$$

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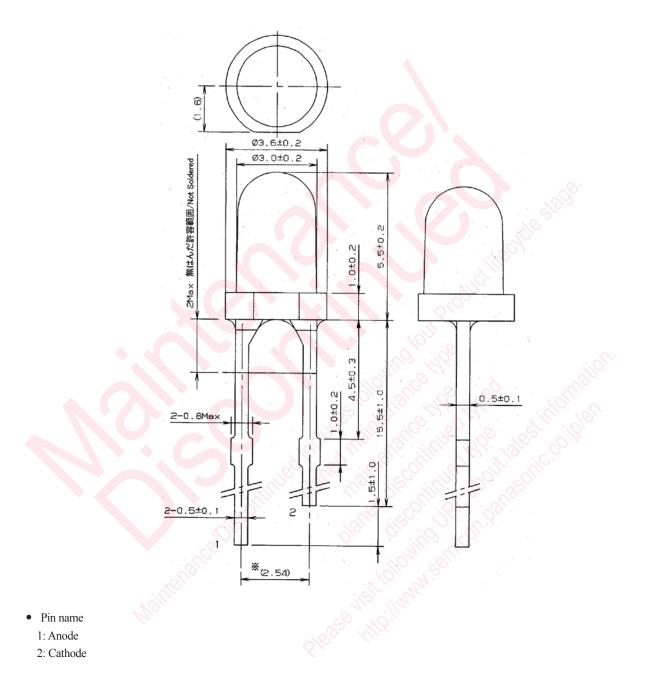
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Package (Unit: mm)

### LEXLTN2S0006



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